PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company STMicroelectronics International N.V		STMicroelectronics International N.V
1.2 PCN No.		MDG/21/12405
1.3 Title of PCN		TSMC Singapore Wafer Fab (SSMC) additional source for STM32F33x 64K listed products
1.4 Product Category		STM32F33x 64K
1.5 Issue date		2021-06-07

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	NEMETH KRISZTINA	
2.1.2 Phone	+49 89460062210	
2.1.3 Email	krisztina.nemeth@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Ricardo Antonio DE SA EARP	
2.1.2 Marketing Manager	Veronique BARLATIER	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change			
3.1 Category	3.2 Type of change	3.3 Manufacturing Location	
	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	TSMC Singapore Wafer Fab SSMC	

4. Description of change			
	Old	New	
4.1 Description	Wafer diffusion plants : - TSMC Taiwan Wafer Fab 3	Wafer diffusion plants : - TSMC Taiwan Wafer Fab 3 - TSMC Singapore Wafer Fab (SSMC) There is no change in the product functionality.	
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no change		

5. Reason / motivation for change		
	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional front-end site to maintain state of the art service level to our customers thanks to extra capacity.	
5.2 Customer Benefit	CAPACITY INCREASE	

6. Marking of parts / traceability of change		
6.1 Description	Traceability of the change is ensured by ST internal tools. Change is visible through diffusion traceability plant, in the marking: - "93" for TSMC Taiwan Wafer Fab 3 - "9C" for TSMC Singapore Wafer Fab SSMC Please refer to PCN 12405 – Additional information attached document.	

7. Timing / schedule		
7.1 Date of qualification results	2021-06-01	
7.2 Intended start of delivery	2021-07-30	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
	12405 MDG-MCD-RER1802 V4.0 - PCN10553 - PCN10803 - PCN10979 - PCN12405 - STM32F - TSMC SSMC 0.18 Xfer - Reliability Evaluation Report.pdf		

8.2	Qua	lificat	tion	report	and
ดเมล	lifica	ation	resi	ults	

Issue Date

9. Attachments (additional documentations)

12405 Public product.pdf 12405 MDG-MCD-RER1802 V4.0 - PCN10553 - PCN10803 - PCN10979 - PCN12405 - STM32F - TSMC SSMC 0.18 Xfer - Reliability Evaluation Report.pdf 12405 PCN12405_Additional information.pdf

10. Affected parts			
10. 1 Current		10.2 New (if applicable)	
10.1.1 Customer Part No 10.1.2 Supplier Part No		10.1.2 Supplier Part No	
	STM32F303C8T6		

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